



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**Notification# 20151207001
Datasheet for ADS1018
Information Only**

Date: 12/8/2015
To: Newark/Farnell PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

**20151207001
Information Only
Attachments**

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
ADS1018IDGST	null
ADS1018IRUGT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20151207001	PCN Date:	12/8/2015
Title:	Datasheet for ADS1018		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

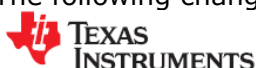
Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification etc.

The product datasheet(s) is being updated as summarized below.

The following change history provides further details.



ADS1018

SBAS526C – NOVEMBER 2012 – REVISED NOVEMBER 2015

Changes from Revision B (Oct 2013) to Revision C	Page No.
<ul style="list-style-type: none"> Added ESD Ratings table, Feature Description section, Noise Performance section, Device Functional Modes section, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section Changed title, Description section, Features section, and block diagram on front page 	1
<ul style="list-style-type: none"> Changed title from Product Family to Device Comparison Table and deleted Package Designator column Updated descriptions and changed name of I/O column in Pin Configurations and Functions table 	4
<ul style="list-style-type: none"> Changed digital input voltage range in Absolute Maximum Ratings table from -0.3V to 5.5V to GND-0.3V to VDD+0.3V because the updated voltage range reflects the device absolute characteristics more accurately Added, previously unstated, minimum specification for TJ, -40°C, in Absolute Maximum Ratings table 	5
<ul style="list-style-type: none"> Added Differential input impedance specification in Electrical Characteristics 	6
<ul style="list-style-type: none"> Changed Condition statement in Timing Requirements: Serial Interface Moved t_{CSDD}, t_{DOPD}, and t_{CSDOZ} parameters from Timing Requirements to Switching Characteristics Moved t_{CSDD} and t_{CSDOZ} values from MIN column to MAX column. It was a human error, the propagation delays (t_{CSDD} and t_{CSDOZ}) of 100 ns are MAX specifications and not MIN specifications 	8
<ul style="list-style-type: none"> Deleted Figure 7, Noise Plot 	9
<ul style="list-style-type: none"> Updated Overview section and deleted "Gain = 2/3, 1, 2, 4, 8, or 16" from Functional Block Diagram 	10
<ul style="list-style-type: none"> Updated Analog Inputs section 	12
<ul style="list-style-type: none"> Updated Full-Scale Range (FSR) and LSB Size section 	13
<ul style="list-style-type: none"> Updated Reset and Power Up section 	15
<ul style="list-style-type: none"> Updated 32-Bit Data Transmission Cycle section 	18
<ul style="list-style-type: none"> Updated Register Maps section 	19
<ul style="list-style-type: none"> Updated Application Information section 	21
<ul style="list-style-type: none"> Updated Figure 21 	24
<ul style="list-style-type: none"> Deleted Thermocouple Measurement With Cold Junction Temperature section, and moved Figure 50 to Typical Application section 	26

Device Family	Change From:	Change To:
ADS1018	SBAS526B	SBAS526C

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/ADS1018>

Reason for Change:			
To more accurately reflect device characteristics.			
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):			
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.			
Changes to product identification resulting from this PCN:			
None.			
Product Affected:			
ADS1018IDGSR	ADS1018IDGST	ADS1018IRUGR	ADS1018IRUGT

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com